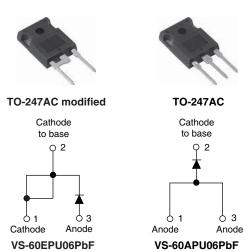


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Vishay Semiconductors

Ultrafast Soft Recovery Diode, 60 A FRED Pt®



PRODUCT SUMMARY	
Package	TO-247AC,
1 ackage	TO-247AC modified (2 pins)
I _{F(AV)}	60 A
V_{R}	600 V
V _F at I _F	1.68 V
t _{rr} typ.	See Recovery table
T _J max.	175 °C
Diode variation	Single die

VS-60APU06-N3

VS-60EPU06-N3

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified according to JEDEC-JESD47
- Halogen-free according to IEC 61249-2-21 definition (-N3 only)





ROHS COMPLIANT HALOGEN FREE

BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION/APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Cathode to anode voltage	V _R		600	V			
Continuous forward current	I _{F(AV)}	T _C = 116 °C	60				
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α			
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120				
Operating junction and storage temperatures	T _J , T _{Stg}		- 55 to 175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-		
	V _F	I _F = 60 A	-	1.35	1.68	V	
Forward voltage		I _F = 60 A, T _J = 125 °C	-	1.20	1.42		
		I _F = 60 A, T _J = 175 °C	-	1.11	1.30		
Poverse leekage current	I _R	$V_R = V_R$ rated	-	-	50		
Reverse leakage current		T _J = 150 °C, V _R = V _R rated	-	-	500	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	39	-	pF	



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 20$	I _F = 1 A, dI _F /dt = 200 A/μs, V _R = 30 V		34	45		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	81	-	ns	
		T _J = 125 °C	$I_F = 60 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	164	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	7.4	-	А	
		T _J = 125 °C		-	17.0	-	A .	
Davaga gaaayan ahaga	0	T _J = 25 °C		-	300	-	nC	
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	1394	-	IIC	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Thermal resistance, junction to case	R _{thJC}		-	-	0.63	K/W	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	-	FX/VV	
Weight			-	5.5	-	g	
vveignt			-	0.2	-	oz.	
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)	
Madda da Sa		Case style TO-247AC modified		60EI	PU06		
Marking device		Case style TO-247AC		60APU06			

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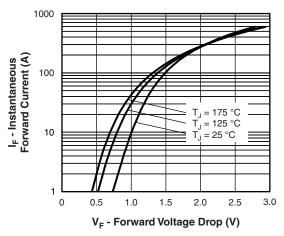


Fig. 1 - Typical Forward Voltage Drop Characteristics

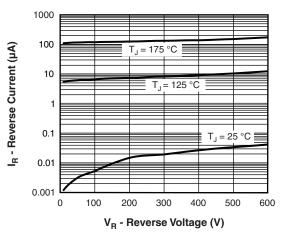


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

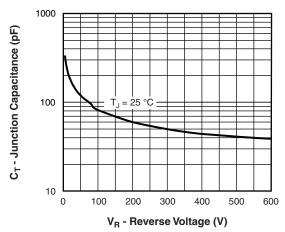


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

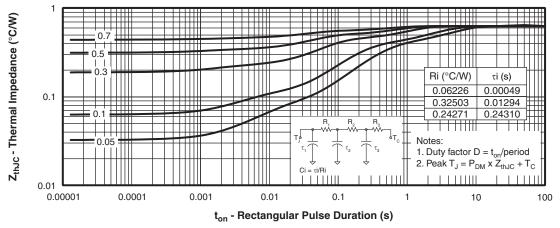


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



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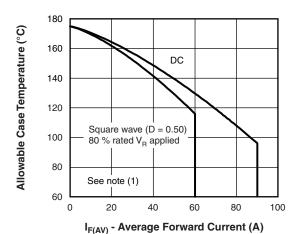


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

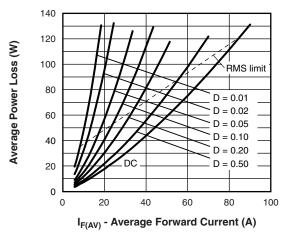


Fig. 6 - Forward Power Loss Characteristics

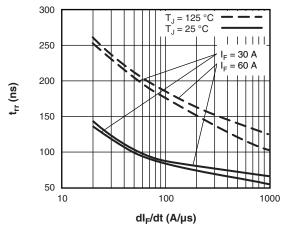


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

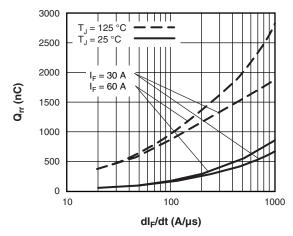


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = Forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

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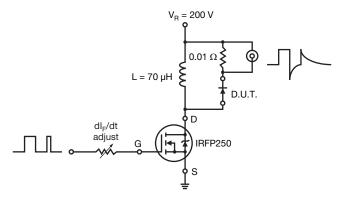
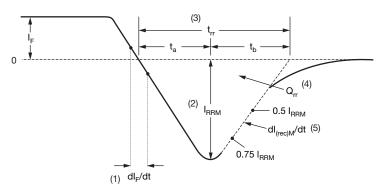


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) ${\rm Q_{rr}}$ area under curve defined by ${\rm t_{rr}}$ and ${\rm I_{RRM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

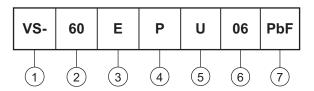
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (60 = 60 A)

Circuit configuration:

• E = Single diode

• A = Single diode, 3 pins

4 - Package:

P = TO-247AC (modified)

5 - Type of silicon:

U = Ultrafast recovery

6 - Voltage rating (06 = 600 V)

7 - Environmental digit:

PbF = Lead (Pb)-free and RoHS compliant

-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

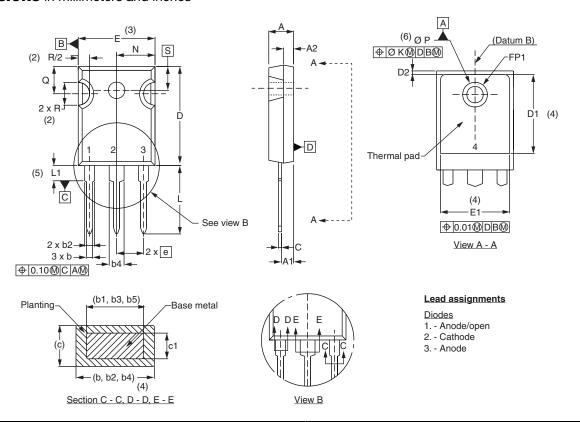
ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-60EPU06PbF	25	500	Antistatic plastic tube				
VS-60EPU06-N3	25	500	Antistatic plastic tube				
VS-60APU06PbF	25	500	Antistatic plastic tube				
VS-60APU06-N3	25	500	Antistatic plastic tube				

LINKS TO RELATED DOCUMENTS				
Dimensions	TO-247AC modified	www.vishay.com/doc?95253		
Differsions	TO-247AC	www.vishay.com/doc?95223		
	TO-247AC modified PbF	www.vishay.com/doc?95255		
Part marking information	TO-247AC modified -N3	www.vishay.com/doc?95442		
Fait marking imormation	TO-247ACPbF	www.vishay.com/doc?95226		
	TO-247AC-N3	www.vishay.com/doc?95007		



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DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.37	0.065	0.094	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.86	0.015	0.034	
c1	0.38	0.76	0.015	0.030	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	MILLIMETERS		INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.72	-	0.540	-	
е	5.46	BSC	0.215	BSC	
FK	2.	54	0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
N	7.62 BSC		0	.3	
ΦР	3.56	3.66	0.14	0.144	
ФР1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	1.78	0.216	
S	5.51	BSC	0.217	BSC	

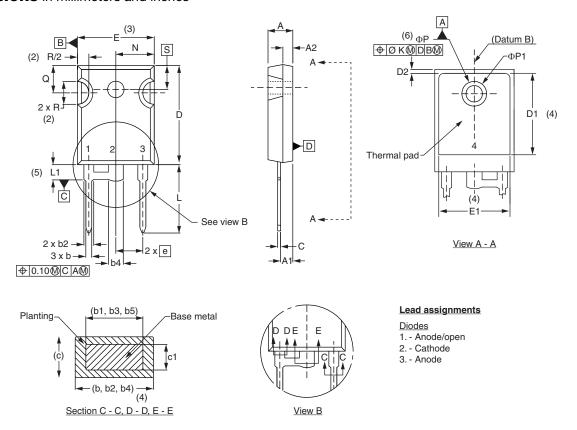
Notes

- $^{(1)}$ Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c



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